



NI/CU CONDUCTIVE FOAM

Laird Technologies' Conductive Foam offers an innovative approach to traditional shielding and grounding by providing X, Y, and Z-axis conductivity, which enhances the shielding effectiveness required to meet the increasing microprocessor speeds of today's computer, aerospace, and telecommunications equipment.

Conductive Foam is designed for low-cycling applications such as input/output (I/O) shielding and other non-shear standard connectors.

FEATURES

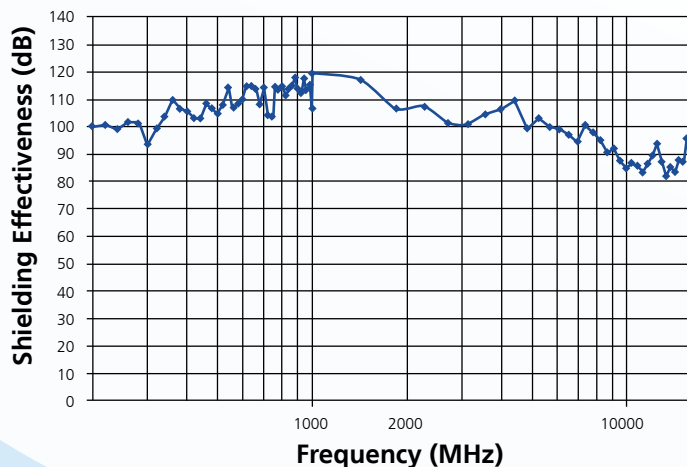
- Halogen-free conductive foam gaskets meet European Union Directives
- UL94 V0 Flammability Rating
- Available with Conductive Pressure Sensitive Adhesive (CPSA)
- Available in 0.039" (1 mm), 0.060" (1.5 mm), 0.079" (2 mm), 0.098 (2.5 mm), 0.125" (3.2 mm) thicknesses, and widths down to 0.250" (6.4 mm)
- The recommended operating compression for Conductive Foam EMI gaskets will vary depending on the size of the gasket. Typically gaskets should be compressed 30% -60% of the original height.

MARKETS

- Cabinet applications
- LCD and Plasma TV
- Medical equipment
- Servers
- Printers
- Laptop computers



**Shielding Effectiveness per MIL-DTL-83528C
V0 Conductive Foam**



global solutions: local support™

USA: +1.866.928.8181

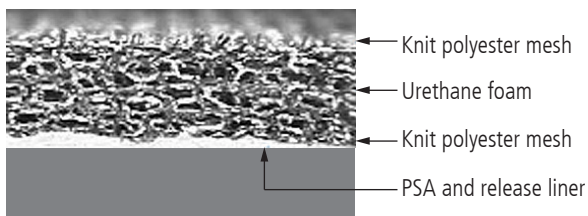
Europe: +49.0.8031.2460.0

Asia: +86.755.2714.1166

SPECIFICATIONS

Item	Unit	Value
Surface Resistivity (ASTM F390)	ohms/square	≤ 0.50
Z-axis Resistivity @ 50% Compression (Laird 130)	ohms	≤ 0.20
Far-field Shielding	effectiveness	(typical)
At 100 MHz	dB	>90
At 1 GHz	dB	>80
Service Temperature	°F (°C)	-40 to 158 (-40 to 70)

COMPOSITION OF PRODUCT



Cross Section
100% Ni/Cu Metallized